

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Canceled) Claim 1 was previously canceled.
2. (Previously Presented) A high-frequency coil device, comprising:
a dielectric substrate; and
a coil formed of a conductive layer embedded in a predetermined coil pattern in the surface of said dielectric substrate, portions of the bottom surface and side surface of said coil being covered by said dielectric substrate, and said coil has other portions which have a gap between a bottom surface of the coil and the substrate.
3. (Canceled) Claim 3 was previously canceled.
4. (Original) The high-frequency coil device as claimed in Claim 2, wherein said resin layer is a polyimide layer or a liquid crystal polymer layer.
5. (Canceled) Claim 5 was previously canceled.
6. (Original) The high-frequency coil device as claimed in claim 4, wherein said plating layer has a multi-layered structure in which a nickel plating layer and a copper plating layer are laminated.
7. (Canceled) Claim 7 was previously canceled.
8. (Canceled) Claim 8 was previously canceled.

9. (Canceled) Claim 9 was previously canceled.

Please add the following new claims:

10. (New) A high-frequency coil device, comprising:
a dielectric substrate; and
a coil formed of a conductive layer, portions of the bottom surface of said coil formed in contact with said dielectric substrate, and said coil has other portions which have a gap between a bottom surface of the coil and the substrate.

11. (New) The high-frequency coil device as claimed in Claim 10, wherein said resin layer is a polyimide layer or a liquid crystal polymer layer.

12. (New) The high-frequency coil device as claimed in claim 11, wherein said plating layer has a multi-layered structure in which a nickel plating layer and a copper plating layer are laminated.